

## Process Change Notification

This is to inform you that a design and/or process change will be implemented to the affected product(s) and this notification is for your information and concurrence. This change is planned to take effect in 90 calendar days from the date of this notification.

Please work with your local Taiwan Semiconductor Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Taiwan Semiconductor Field Quality Service or Customer Quality Engineer within 45 days of receipt of this notification if you require any additional data or samples.

**PCN No: PCN22003**

**Title:** SOD123F Change of EMC, die size and bonding wire

**Issue Date: 2022/2/22**

If you have any questions concerning this change, please contact:

**PCN Coordinator**

Name : Delia Chang  
E-Mail: [delia.chang@mail.ts.com.tw](mailto:delia.chang@mail.ts.com.tw)  
Phone: +886-3-928-5117 Ext. 315

**PCN Originator**

Name : Melinda Luo  
E-mail: [Melinda\\_luo@mail.tew.com.cn](mailto:Melinda_luo@mail.tew.com.cn)  
Phone: 0086-22-59816699 Ext : 2032

**Reliability Engineer**

Name : Aiping Zhang  
E-mail: [aiping@mail.tew.com.cn](mailto:aiping@mail.tew.com.cn)  
Phone: 0086-22-59816699 Ext : 2030

**PCN Type:** Change of EMC, die size and bonding wire

**Effectivity:**

Expected 1st device shipment date: 2022/5/23  
Last order date: 2022/8/21  
Last delivery date: 2023/8/21

**Product Category (Description):**

Devices of SOD-123F package supplied by Taiwan Semiconductor Co., Ltd and manufactured by its qualified supplier.

The full lists of products affected are listed in the "List of Affected Devices" section.

**Description of Change:**

This PCN is to inform customers regarding the initiated changes by TSC supplier (Vendor code 4999) for devices manufactured in SOD-123F to ensure the continuity of supply and guarantee commitment on customer service and satisfaction.

Reliability test performance on the representative part numbers are to ensure no change on the device functionality or electrical specifications in the datasheet. Refer to reliability test report below:

**BOM Comparison**

## 1. Die size change

| Item                       | From        | To                      | Remarks   |
|----------------------------|-------------|-------------------------|-----------|
| Die Size (BZT52Series)     | 0.26*0.26mm | 0.33*0.33mm             | Different |
| Die Size (MMSZ5221BSeries) | 0.26*0.26mm | 0.32*0.32mm/0.33*0.33mm | Different |

## 2. EMC and bonding wire change

| Item             | From      | To     | Remarks   |
|------------------|-----------|--------|-----------|
| Wire             | Au        | Cu     | Different |
| Molding Compound | SG-8300CS | KHG600 | Different |

**Qualification and Reliability Result:**

## 1. Electrical test comparison

| P/N: BZT52B5V1 | ITEM           | VZ(V)      | ZZT ( Ω ) | ZZK ( Ω ) | IR(nA)    | VF ( V ) | Result                      |
|----------------|----------------|------------|-----------|-----------|-----------|----------|-----------------------------|
|                | TEST Condition | IZ=5mA     | Izt=5mA   | Izk=1mA   | VR=2V     | IF=10mA  |                             |
|                | SPEC.          | 5V<VZ<5.2V | ZZT<60Ω   | ZZK<451Ω  | IR<1800nA | VF<1V    |                             |
| Before         | MIN            | 5.11       | 4.94      | 36.80     | 1.92      | 0.82     | Both can meet specification |
|                | MAX            | 5.12       | 6.02      | 39.90     | 7.21      | 0.83     |                             |
|                | AVG.           | 5.12       | 5.33      | 38.64     | 4.06      | 0.82     |                             |
|                | CPK            | 10.51      | 89.01     | 223.47    | 412.15    | 35.75    |                             |
| After          | MIN            | 5.09       | 24.94     | 268.80    | 48.72     | 0.79     |                             |
|                | MAX            | 5.11       | 26.12     | 274.30    | 53.09     | 0.80     |                             |
|                | AVG.           | 5.10       | 25.47     | 271.39    | 51.06     | 0.79     |                             |
|                | CPK            | 7.82       | 36.16     | 41.09     | 482.22    | 80.77    |                             |

| P/N: MMSZ5252B | ITEM           | VZ(V)          | ZZT ( Ω ) | ZZK ( Ω )  | IR(nA)   | VF ( V ) | Result                      |
|----------------|----------------|----------------|-----------|------------|----------|----------|-----------------------------|
|                | TEST Condition | Iz=5.2mA       | Izt=5.2mA | Izk=0.25mA | VR=18V   | IF=10mA  |                             |
|                | SPEC.          | 22.8V<VZ<25.2V | ZZT<33Ω   | ZZK<600Ω   | IR<100nA | VF<0.9V  |                             |
| Before         | MIN            | 23.76          | 13.69     | 49.60      | 0.01     | 0.78     | Both can meet specification |
|                | MAX            | 23.93          | 14.26     | 95.60      | 2.58     | 0.79     |                             |
|                | AVG.           | 23.87          | 13.99     | 65.90      | 1.43     | 0.79     |                             |
|                | CPK            | 10.03          | 38.84     | 13.16      | 39.37    | 30.53    |                             |
| After          | MIN            | 23.63          | 9.13      | 80.40      | 0.11     | 0.775    |                             |
|                | MAX            | 23.87          | 9.92      | 235.60     | 0.54     | 0.784    |                             |
|                | AVG.           | 23.74          | 9.44      | 143.51     | 0.40     | 0.780    |                             |
|                | CPK            | 4.61           | 36.10     | 3.23       | 474.94   | 16.19    |                             |

Conclusion: The change of die size, molding compound and bonding wire will not affect the product electrical performance and product reliability.

## 2. Qualification and Reliability Result:

### Qualification Vehicle:

BZT52B75, BZT52C75, MMSZ5262B, 1N4448W, BAV21W, B0520LWF, B0540WF

Package: SOD-123F

| NO. | Test                                | Test Conditions/ Standard  | No. of Lots | Sample Size | Result |
|-----|-------------------------------------|--|-------------|-------------|--------|
| 1   | Pre-conditioning                    | JESD22-A113, J-STD-020<br>Temp. Cycle: -40 °C ~ +60 °C,<br>5 cycles<br>Bake: 125 °C for 24 hrs.<br>Soak:<br>> MSL1: 85 °C RH: 85 %, 168 Hrs<br>IR Reflow Temperature: 260 (+5/-0)°C @<br>3x cycles | 7           | 308         | PASS   |
| 2   | Steady state operational            | MIL-STD-750-1 M1038 Condition B(Zeners)<br>rated IZ max, Tj=150°C, 1000hrs   | 3           | 77          | PASS   |
| 3   | High Temperature Reverse Bias       | JESD22-A108, MIL-STD-750 M1038<br>Tj=Tjmax, at least 80% rated Vr, 1000hrs   | 4           | 77          | PASS   |
| 4   | Temperature Cycling                 | JESD22-A104<br>'-55(-10/+0)°C/15min to 150(+15/-0)°C/15min, 1000 cycles  | 7           | 77          | PASS   |
| 5   | High Temperature Storage Test       | JESD22-A103, 150°C, 1000hrs  | 7           | 77          | PASS   |
| 6   | UHAST                               | JESD22-A118, Ta=130°C, 85%RH, 96hrs  | 7           | 77          | PASS   |
| 7   | HAST                                | JESD22-A110<br>Ta=130°C/85%RH 80% rated Vr up to 42Vmax, 96hrs   | 7           | 77          | PASS   |
| 8   | Intermittent Operational Life       | Ta=25°C, ΔTj >= 100 °C, 2 mins ON + 2 mins OFF , 6000 cycle  | 7           | 77          | PASS   |
| 9   | Destructive Physical Analysis (DPA) | JESD22-A104, JESD22-B116<br>TC passed choose 2pcs of the 1 lot<br>HAST or H3TRB passed choose 2 pcs of the 1 lot:<br>Visual inspection, SAM, X-ray, decapsulation than Visual inspection           | 7           | 4           | PASS   |

|    |                           |  |   |    |              |
|----|---------------------------|--|---|----|--------------|
| 10 | Resistance to Solder Heat | JESD22-A111 SMD, B-106 PTH<br>Pb free: 260(+5/-0)°C , 10 sec (+2/-0)         | 7 | 10 | PASS         |
| 11 | ESD Characterization      | HBM JS-001 10pcs for each ESD level,<br>(C=100pf R=1500Ω)                    | 3 | 30 | Cap.:8K<br>V |
|    |                           | CDM JS-002 10pcs for each ESD level<br>allowed.                              | 3 | 30 | Cap.:2K<br>V |
| 12 | Solderability             | J-STD-002<br>245 °C ± 5 °C (Pb-free) 5 sec                                   | 7 | 10 | PASS         |
| 13 | C-SAM                     | J-STD-035, AEC-Q006, T0, Post-PC &<br>Post-TC; T0, Post-PC & Post-HAST rej=0 | 5 | 22 | PASS         |
| 14 | Wire Bond Pull            | MIL-STD-750 per assembly spec CPK≥<br>1.33                                   | 5 | 30 | PASS         |
| 15 | Wire Bond Shear           | MIL-STD-750 per assembly spec CPK≥<br>1.33                                   | 5 | 30 | PASS         |
| 16 | Die shear                 | MIL-STD-750 per assembly spec  | 3 | 10 | PASS         |
| 17 | Thermal Resistance        | JESD24, per product datasheet  | 3 | 5  | PASS         |

Conclusion: The combination of new die size, molding compound and wire can ensure the quality and reliability of final product.

#### Effect of Change:

There is no impact on the form, fit, function, reliability or processability. This change will guarantee Taiwan Semiconductor commitment on customer service and satisfaction through continuous improvement.

#### List of Affected Devices:

| Package  | Part Number | Package  | Part Number | Package  | Part Number |
|----------|-------------|----------|-------------|----------|-------------|
| SOD-123F | BZT52B2V4   | SOD-123F | BZT52B10    | SOD-123F | BZT52B43    |
| SOD-123F | BZT52B2V7   | SOD-123F | BZT52B11    | SOD-123F | BZT52B47    |
| SOD-123F | BZT52B3V0   | SOD-123F | BZT52B12    | SOD-123F | BZT52B51    |
| SOD-123F | BZT52B3V3   | SOD-123F | BZT52B13    | SOD-123F | BZT52B56    |
| SOD-123F | BZT52B3V6   | SOD-123F | BZT52B15    | SOD-123F | BZT52B62    |
| SOD-123F | BZT52B3V9   | SOD-123F | BZT52B16    | SOD-123F | BZT52B68    |
| SOD-123F | BZT52B4V3   | SOD-123F | BZT52B18    | SOD-123F | BZT52B75    |
| SOD-123F | BZT52B4V7   | SOD-123F | BZT52B20    | SOD-123F | BZT52C2V4   |
| SOD-123F | BZT52B5V1   | SOD-123F | BZT52B22    | SOD-123F | BZT52C2V7   |
| SOD-123F | BZT52B5V6   | SOD-123F | BZT52B24    | SOD-123F | BZT52C3V0   |
| SOD-123F | BZT52B6V2   | SOD-123F | BZT52B27    | SOD-123F | BZT52C3V3   |
| SOD-123F | BZT52B6V8   | SOD-123F | BZT52B30    | SOD-123F | BZT52C3V6   |
| SOD-123F | BZT52B7V5   | SOD-123F | BZT52B33    | SOD-123F | BZT52C3V9   |
| SOD-123F | BZT52B8V2   | SOD-123F | BZT52B36    | SOD-123F | BZT52C4V3   |
| SOD-123F | BZT52B9V1   | SOD-123F | BZT52B39    | SOD-123F | BZT52C4V7   |
| SOD-123F | BZT52C5V1   | SOD-123F | MMSZ5221B   | SOD-123F | MMSZ5259B   |
| SOD-123F | BZT52C5V6   | SOD-123F | MMSZ5225B   | SOD-123F | MMSZ5260B   |
| SOD-123F | BZT52C6V2   | SOD-123F | MMSZ5226B   | SOD-123F | MMSZ5261B   |
| SOD-123F | BZT52C6V8   | SOD-123F | MMSZ5227B   | SOD-123F | MMSZ5262B   |
| SOD-123F | BZT52C7V5   | SOD-123F | MMSZ5228B   | SOD-123F | 1N4148W     |
| SOD-123F | BZT52C8V2   | SOD-123F | MMSZ5229B   | SOD-123F | 1N4448W     |
| SOD-123F | BZT52C9V1   | SOD-123F | MMSZ5230B   | SOD-123F | 1N914BW     |

| Package  | Part Number | Package  | Part Number | Package  | Part Number |
|----------|-------------|----------|-------------|----------|-------------|
| SOD-123F | BZT52C10    | SOD-123F | MMSZ5231B   | SOD-123F | BAV19W      |
| SOD-123F | BZT52C11    | SOD-123F | MMSZ5232B   | SOD-123F | BAV20W      |
| SOD-123F | BZT52C12    | SOD-123F | MMSZ5234B   | SOD-123F | BAV21W      |
| SOD-123F | BZT52C13    | SOD-123F | MMSZ5235B   | SOD-123F | B0520LWF    |
| SOD-123F | BZT52C15    | SOD-123F | MMSZ5236B   | SOD-123F | B0530WF     |
| SOD-123F | BZT52C16    | SOD-123F | MMSZ5237B   | SOD-123F | B0540WF     |
| SOD-123F | BZT52C18    | SOD-123F | MMSZ5239B   |          |             |
| SOD-123F | BZT52C20    | SOD-123F | MMSZ5240B   |          |             |
| SOD-123F | BZT52C22    | SOD-123F | MMSZ5241B   |          |             |
| SOD-123F | BZT52C24    | SOD-123F | MMSZ5242B   |          |             |
| SOD-123F | BZT52C27    | SOD-123F | MMSZ5243B   |          |             |
| SOD-123F | BZT52C30    | SOD-123F | MMSZ5244B   |          |             |
| SOD-123F | BZT52C33    | SOD-123F | MMSZ5245B   |          |             |
| SOD-123F | BZT52C36    | SOD-123F | MMSZ5246B   |          |             |
| SOD-123F | BZT52C39    | SOD-123F | MMSZ5248B   |          |             |
| SOD-123F | BZT52C43    | SOD-123F | MMSZ5250B   |          |             |
| SOD-123F | BZT52C47    | SOD-123F | MMSZ5251B   |          |             |
| SOD-123F | BZT52C51    | SOD-123F | MMSZ5252B   |          |             |
| SOD-123F | BZT52C56    | SOD-123F | MMSZ5254B   |          |             |
| SOD-123F | BZT52C62    | SOD-123F | MMSZ5256B   |          |             |
| SOD-123F | BZT52C68    | SOD-123F | MMSZ5257B   |          |             |
| SOD-123F | BZT52C75    | SOD-123F | MMSZ5258B   |          |             |